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Autore	PONTIERI, Ernesto
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Nota di contenuto	LED Packaging for Lighting Applications: Design, Manufacturing and Testing; Contents; Foreword By Magnus George Craford; Foreword By C. P. Wong; Foreword By B. J. Lee; Preface; Acknowledgments; About the Authors; 1 Introduction; 1.1 Historical Evolution of Lighting Technology; 1.2 Development of LEDs; 1.3 Basic Physics of LEDs; 1.3.1 Materials; 1.3.2 Electrical and Optical Properties; 1.3.3 Mechanical and Thermal Properties; 1.4 Industrial Chain of LED; 1.4.1 LED Upstream Industry; 1.4.2 LED Midstream Industry; 1.4.3 LED Downstream Industry; 1.5 Summary; References 2 Fundamentals and Development Trends of High Power LED Packaging2.1 Brief Introduction to Electronic Packaging; 2.1.1 About

Electronic Packaging and Its Evolution; 2.1.2 Wafer Level Packaging, More than Moore, and SiP; 2.2 LED Chips; 2.2.1 Current Spreading Efficiency; 2.2.2 Internal Quantum Efficiency; 2.2.3 High Light Extraction Efficiency; 2.3 Types and Functions of LED Packaging; 2.3.1 Low Power LED Packaging; 2.3.2 High Power LED Packaging; 2.4 Key Factors and System Design of High Power LED Packaging; 2.5 Development Trends and Roadmap; 2.5.1 Technology Needs; 2.5.2 Packaging Types
2.6 SummaryReferences; 3 Optical Design of High Power LED Packaging Module; 3.1 Properties of LED Light; 3.1.1 Light Frequency and Wavelength; 3.1.2 Spectral Distribution; 3.1.3 Flux of Light; 3.1.4 Lumen Efficiency; 3.1.5 Luminous Intensity, Illuminance and Luminance; 3.1.6 Color Temperature, Correlated Color Temperature and Color Rendering Index; 3.1.7 White Light LED; 3.2 Key Components and Packaging Processes for Optical Design; 3.2.1 Chip Types and Bonding Process; 3.2.2 Phosphor Materials and Phosphor Coating Processes; 3.2.3 Lens and Molding Process; 3.3 Light Extraction
3.4 Optical Modeling and Simulation3.4.1 Chip Modeling; 3.4.2 Phosphor Modeling; 3.5 Phosphor for White LED Packaging; 3.5.1 Phosphor Location for White LED Packaging; 3.5.2 Phosphor Thickness and Concentration for White LED Packaging; 3.5.3 Phosphor for Spatial Color Distribution; 3.6 Collaborative Design; 3.6.1 Co-design of Surface Micro-Structures of LED Chips and Packages; 3.6.2 Application Specific LED Packages; 3.7 Summary; References; 4 Thermal Management of High Power LED Packaging Module; 4.1 Basic Concepts of Heat Transfer; 4.1.1 Conduction Heat Transfer
4.1.2 Convection Heat Transfer4.1.3 Thermal Radiation; 4.1.4 Thermal Resistance; 4.2 Thermal Resistance Analysis of Typical LED Packaging; 4.3 Various LED Packages for Decreasing Thermal Resistance; 4.3.1 Development of LED Packaging; 4.3.2 Thermal Resistance Decrease for LED Packaging; 4.3.3 SiP/COB LED Chip Packaging Process; 4.4 Summary; References; 5 Reliability Engineering of High Power LED Packaging; 5.1 Concept of Design for Reliability (DfR) and Reliability Engineering; 5.1.1 Fundamentals of Reliability; 5.1.2 Life Distribution; 5.1.3 Accelerated Models; 5.1.4 Applied Mechanics
5.2 High Power LED Packaging Reliability Test

Sommario/riassunto

"This book provides quantitative methods for optical, thermal, reliability modelling and simulation so that predictive quantitative modelling can be achieved"--